



Press Release

Kuala Lumpur, 2 May 2012 – Unisem (M) Berhad today announced results for the first quarter ended 31 March 2012 (**1Q12**).

The Group recorded revenue of RM256.6 million (approx. US\$83.6 million) for 1Q12, 12.1 percent decline from RM292.0 million (approx. US\$95.6 million) achieved in the same quarter a year ago (**1Q11**). The Group recorded a net loss of RM13.7 million (approx. US\$4.4 million) compared to net profit of RM5.4 million (approx. US\$1.7 million) achieved in 1Q11.

Compared to the preceding quarter (**4Q11**) Group revenue declined 6.1 percent from RM273.2 million (approx. US\$86.9 million) and net loss increased RM11.0 million (approx. US\$3.6 million) from net loss of RM2.6 million (approx. US\$828,000).

The decline in the revenue and profit of the Group for 1Q12 was principally attributable to reduced sales volume, a one-time retrenchment costs of RM5.7 million (approx. US\$1.8 million) arising from an efficiency/redundancy exercise at PT Unisem and higher depreciation charges.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 1Q12 came in at RM31.1 million (approx. US\$10.1 million) a decline from RM41.3 million (approx. US\$13.7 million) in 4Q11.

Equipment capacity utilization averaged at about 60 percent for the group in 1Q12. Group capital expenditure incurred in 1Q12 was about RM17.8 million (approx. US\$5.8 million), principally for purchase of assembly and final test equipment for Unisem Chengdu and Unisem (M) Berhad.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "We expect the revenue and earnings of the Group in the second quarter to improve from that achieved in the first quarter and to continue to improve to the end of the financial year. "

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 10,000 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.